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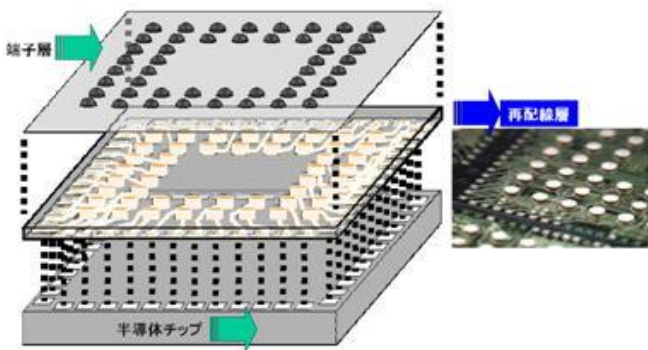
1998

Development of the WL-CSP formed on wafers

~ Packaging ~

Oki started the development of WL-CSP (Wafer Level Chip Scale Package) from around 1998 and applied it to ICs and LSIs for mobile phones around 2005. Re-wiring was done on a wafers that was finished with diffusion process, and small sized package was formed. There were features such as the merits of compact mounting, less inductance and resistance, integrating of capacitors and thin film coils, which made the application of high frequency ICs and embedding in printed circuit board easy.

The same type of technique was developed also by Hitachi and was called WPP (Wafer Process Package).



Assembly & test processes are completed in wafer form

